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General Information

Series	KONNEKT Comm COG
Style	KONNEKT
Description	SMD, MLCC, KONNEKT, Ultra-Stable, Class I
Features	High Density Packaging
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	77.62 mg
Chip Size	1206-2
Shelf Life	78 Weeks
MSL	1

Dimensions

L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	3.2mm +/-0.4mm
B	0.5mm +/-0.25mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	500

Specifications

Capacitance	0.044 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 PPM/C
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	22.727 GOhms

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